



HM2222A

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HM2222A is designed for general purpose amplifier and high speed, medium-power switching applications.

Features

- Low collector saturation voltage
- High speed switching
- For complementary use with PNP type HPN2907A

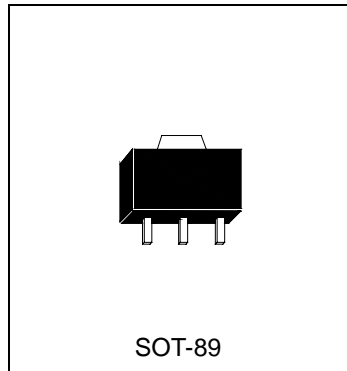
Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 1.2 W
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage 75 V
VCES Collector to Emitter Voltage 40 V
VEBO Emitter to Base Voltage 6 V
IC Collector Current 600 mA

Characteristics (Ta=25°C)

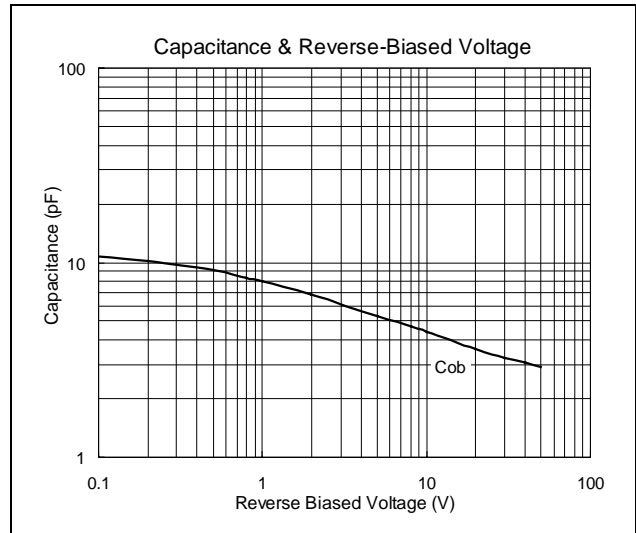
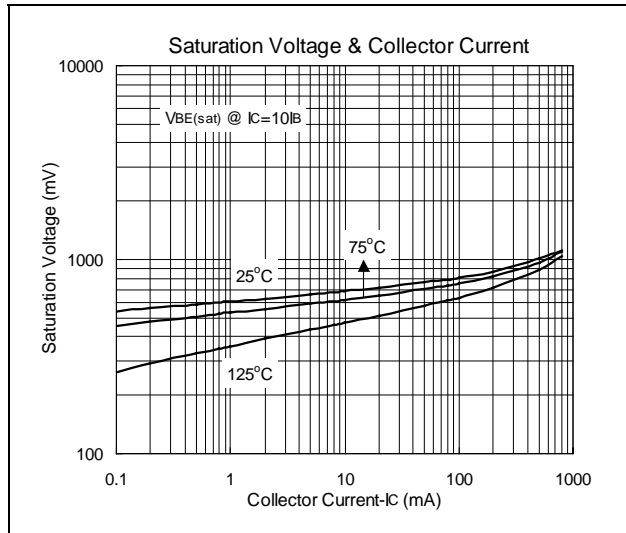
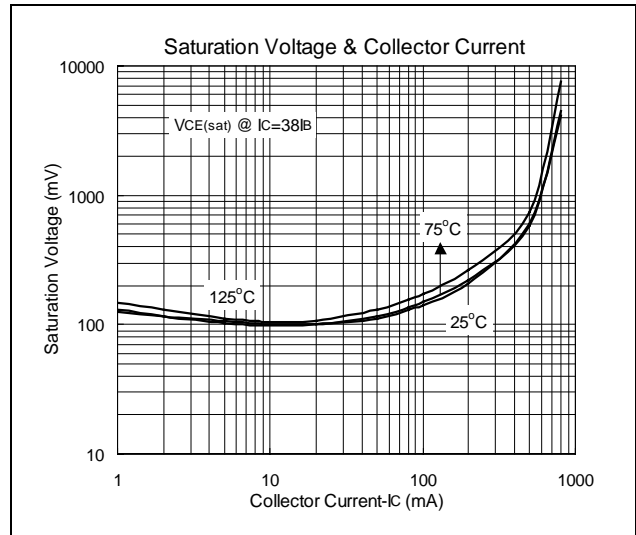
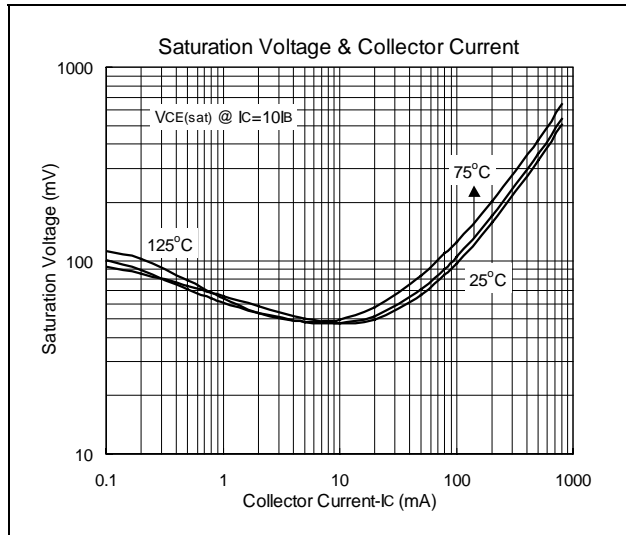
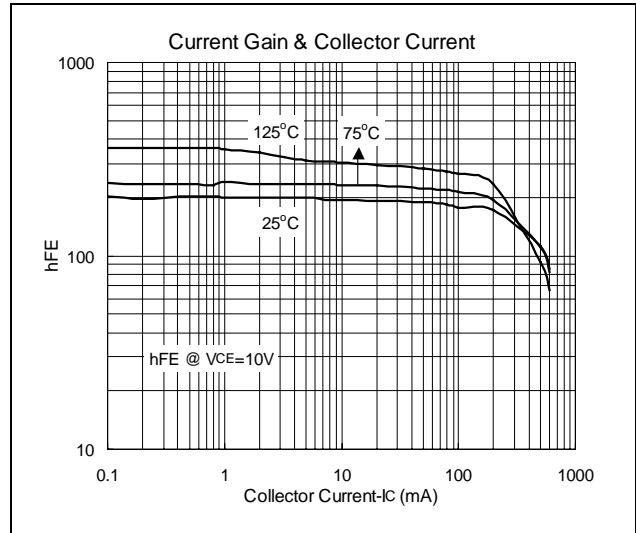
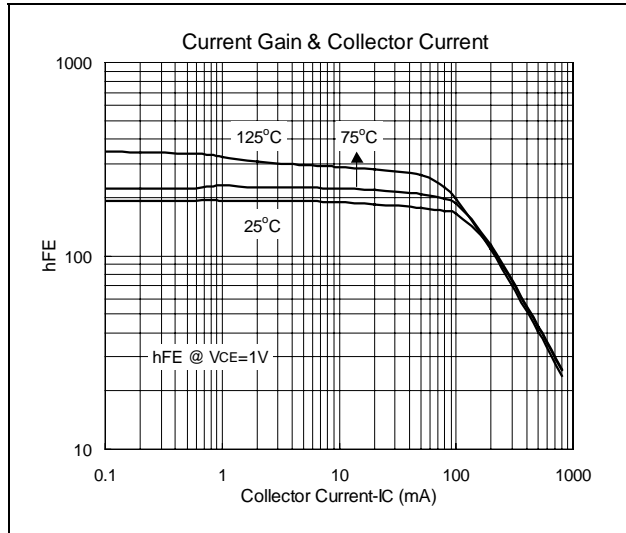
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	75	-	-	V	IC=10uA
BVCEO	40	-	-	V	IC=10mA
BVEBO	6	-	-	V	IE=10uA
ICBO	-	-	10	nA	VCB=60V
ICEX	-	-	10	nA	VCB=60V, VEB(off)=3V
IEBO	-	-	50	nA	VEB=3V
*VCE(sat)1	-	-	300	mV	IC=150mA, IB=15mA
*VCE(sat)2	-	-	1	V	IC=500mA, IB=50mA
*VBE(sat)1	-	-	1.2	V	IC=150mA, IB=15mA
*VBE(sat)2	-	-	2	V	IC=500mA, IB=50mA
*hFE1	35	-	-		VCE=10V, IC=100uA
*hFE2	50	-	-		VCE=10V, IC=1mA
*hFE3	75	-	-		VCE=10V, IC=10mA
*hFE4	100	-	300		VCE=10V, IC=150mA
*hFE5	40	-	-		VCE=10V, IC=500mA
*hFE6	50	-	-		VCE=1V, IC=150mA
fT	300	-	-	MHz	VCE=20V, IC=20mA, f=100MHz

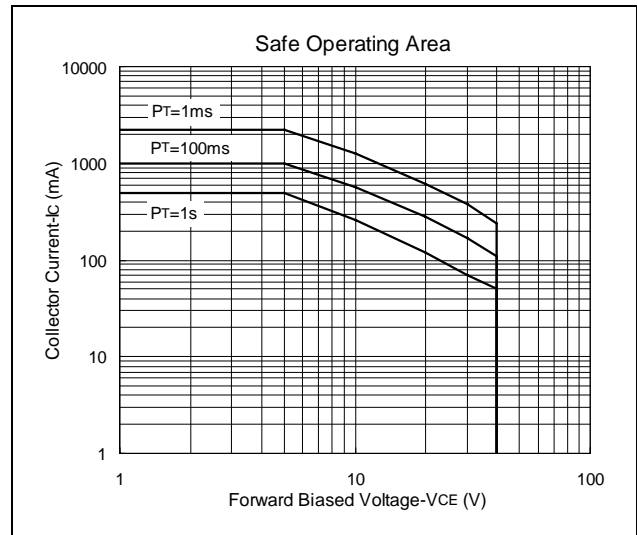
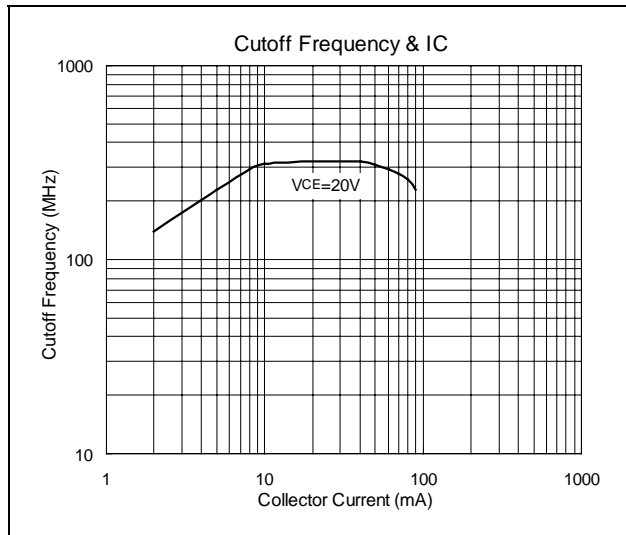
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%





Characteristics Curve







SOT-89 Dimension

Marking:

Date Code → H M
2 2 2 A
 Laser Marking

Style: Pin 1.Base 2.Collector 3.Emitter

3-Lead SOT-89 Plastic Surface Mounted Package
 HSMC Package Code: M

*: typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
 - 2.Controlling dimension: millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: L94V-0

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Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel: 886-3-5983621~5 Fax: 886-3-5982931